Product Change Notification: DSNO-07SNHX825

Date:

25-Sep-2026

Product Category:

Memory

Notification Subject:

CCB 8400.001 Initial Notice: Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound for selected 24AA1025, 24AA1026, 24AA128, 24AA256, 24AA32A, 24AA32AF, 24AA512, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS512, 24CS64, 24CSM01, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC1025, 24FC1026, 24FC128, 24FC256, 24FC512, 24FC64, 24FC64F, 24LC1025, 24LC1026, 24LC128, 24LC256, 24LC32A, 24LC32AF, 24LC512, 24LC64, 24LC64F, 25CSM01, AT24C128C, AT24C256C, AT24C32D, AT24C32E, AT24C512C, AT24C64B, AT24C64D, AT24CM01 and AT25M01 device families available in 8L SOIC (.150in) package at MTAI assembly site.

Affected CPNs:

DSNO-07SNHX825_Affected_CPN_09252026.pdf
DSNO-07SNHX825_Affected_CPN_09252026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound for selected 24AA1025, 24AA1026, 24AA128, 24AA256, 24AA32A, 24AA32AF, 24AA512, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS512, 24CS64, 24CSM01, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC1025, 24FC1026, 24FC128, 24FC256, 24FC512, 24FC64, 24FC64F, 24LC1025, 24LC1026, 24LC128, 24LC256, 24LC32A, 24LC32AF, 24LC512, 24LC64, 24LC64F, 25CSM01, AT24C128C, AT24C256C, AT24C32D, AT24C32E, AT24C512C, AT24C64B, AT24C64D, AT24CM01 and AT25M01 device families available in 8L SOIC (.150in) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change		Post Change			Change (Yes / No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)		Microchip Technology Thailand (HQ) (MTAI)			No
Wire Material	CuPdAu		CuPdAu			No
Die Attach Material	8390A	QMI519	8390A	QMI519	CRM-1064L	Yes
Molding Compound Material	G600V		G600V		G630AY	Yes
Lead-Frame Material	CDA194		CDA194			No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CRM-1064L as an additional die attach material and G630AY as an additional mold compound at MTAI assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: September 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2026				
Work Week	36	37	38	39	40
Initial PCN Issue Date			**x**		
Qual Report Availability					x
Final PCN Issue Date					x

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: September 15, 2026: Issued initial notification.
September 25, 2026: Re-issued initial notification to remove wire sweep test from the Qual Plan.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-07SNHX825_Qual_Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

24CS32T-I/SN

AT24C128C-SSHM-TCODTW

24LC128T-I/SNCODTW

25CSM01-E/SN

AT25M01-SSHM-B

25CSM01-I/SN

AT25M01-SSHM-T

AT24CM01-SSHD-B

24FC1026-I/SN

24LC1026-I/SN

24AA1026T-I/SN

AT24CM01-SSHM-T

AT24CM01-SSHD-T

24FC1026T-I/SN

24CSM01-I/SN

24CSM01T-I/SN

24CSM01T-E/SN

24FC128-E/SN

24LC128-E/SN

24CS128-E/SN

24AA128-I/SN

AT24C128C-SSHM-B

24FC128-I/SN

24LC128-I/SN

24CS128-I/SN

24AA64T/SN

24LC32AT/SN

AT24C32D-SSHM-T

AT24C32D-SSHMFD-T

24FC1025-I/SN

24LC1025-I/SN

24AA1025T-I/SN

24FC64FT-I/SN

24LC32AT-I/SN

24LC32AFT-I/SN

24LC64T-I/SN

24LC64FT-I/SN

24CS512-I/SN

24LC32A/SN

24AA64-E/SN

24LC32A-E/SN

24LC32AF-E/SN

24LC64-E/SN

24LC64F-E/SN

24CS32-E/SN

24CS64-E/SN

AT24C32D-SSHM-B

AT24C32E-SSHM-B

AT24C64BN-10SU-2.7

AT24C64D-SSHM-B

24AA32A-I/SN

24AA32AF-I/SN

24AA64-I/SN

24AA64F-I/SN

24FC64-I/SN

24FC64F-I/SN

24LC32A-I/SN

24LC32AF-I/SN

24LC64-I/SN

24LC64F-I/SN

24CS32-I/SN

24CS64-I/SN

24CS64T-I/SN

24AA64T-E/SN

24LC32AT-E/SN

24LC32AFT-E/SN

24LC64T-E/SN

24LC64FT-E/SN

24CS32T-E/SN

24CS64T-E/SN

AT24C64D-SSHM-TCODTW

AT24C32E-SSHM-TCODTW

24LC256-E/SN

24AA256-E/SN

24FC256-E/SN

24CS256-E/SN

24LC256-I/SN

24AA256-I/SN

24FC256-I/SN

24CS256-I/SN

AT24C256C-SSHL-B

24AA128T-I/SN

AT24C128C-SSHM-T

24FC128T-I/SN

24LC128T-I/SN

24CS128T-I/SN

24FC128T-E/SN

24LC128T-E/SN

24CS128T-E/SN

24LC256T-I/SN

24AA256T-I/SN

24FC256T-I/SN

24CS256T-I/SN

AT24C256C-SSHL-T

24LC256T-E/SN

24AA256T-E/SN

24FC256T-E/SN

24CS256T-E/SN

24AA256T-E/SNCODTW

AT24C256C-SSHL-TCODTW

24LC256T-I/SNCODTW

24AA256T-I/SNCODTW

24LC512-E/SN

24CS512-E/SN

24LC512-I/SN

24AA512-I/SN

24FC512-I/SN

AT24C512C-SSHD-B

AT24C512C-SSHM-B

25CSM01T-I/SN

25CSM01T-E/SN

24CW1280-I/SN

24CW1280T-I/SN

24CW160-I/SN

24CW320-I/SN

24CW640-I/SN

24CW160T-I/SN

24CW320T-I/SN

24CW640T-I/SN

24LC1025-E/SN

24AA1025-I/SN

AT24C32E-SSHM-T

AT24C64BN-10SU-2.7-T

AT24C64D-SSHM-T

AT24C64D-SSHMGT-T

24AA32AT-I/SN

24AA32AFT-I/SN

24AA64T-I/SN

24AA64FT-I/SN

24LC1026T-I/SN

24LC1026T-E/SN

24LC1026-I/SNCODTW

24AA64/SN

24LC512T-I/SN

24AA512T-I/SN

24FC512T-I/SN

AT24C512C-SSHD-T

AT24C512C-SSHM-T

24CS512T-I/SN

24LC512T-E/SN

24CS512T-E/SN

24AA512T-I/SNCODTW

24LC512T-I/SNCODTW

AT24C512C-SSHM-TCODTW

AT24C512C-SSHD-TCODTW

24CSM01-E/SN

24FC64T-I/SN

24FC1025T-I/SN

24LC1025T-I/SN

24LC1025T-I/SNCODTW

24LC1025T-E/SN

24FC1025T-I/SNCODTW

24LC1026-E/SN

24AA1026-I/SN

AT24CM01-SSHM-B



MICROCHIP

QUALIFICATION PLAN SUMMARY

PCN#: DSNO-07SNHX825

Date:
September 17, 2026

Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound for selected 24AA1025, 24AA1026, 24AA128, 24AA256, 24AA32A, 24AA32AF, 24AA512, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS512, 24CS64, 24CSM01, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC1025, 24FC1026, 24FC128, 24FC256, 24FC512, 24FC64, 24FC64F, 24LC1025, 24LC1026, 24LC128, 24LC256, 24LC32A, 24LC32AF, 24LC512, 24LC64, 24LC64F, 25CSM01, AT24C128C, AT24C256C, AT24C32D, AT24C32E, AT24C512C, AT24C64B, AT24C64D, AT24CM01 and AT25M01 device families available in 8L SOIC (.150in) package at MTAI assembly site.

Purpose: Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound for selected 24AA1025, 24AA1026, 24AA128, 24AA256, 24AA32A, 24AA32AF, 24AA512, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS512, 24CS64, 24CSM01, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC1025, 24FC1026, 24FC128, 24FC256, 24FC512, 24FC64, 24FC64F, 24LC1025, 24LC1026, 24LC128, 24LC256, 24LC32A, 24LC32AF, 24LC512, 24LC64, 24LC64F, 25CSM01, AT24C128C, AT24C256C, AT24C32D, AT24C32E, AT24C512C, AT24C64B, AT24C64D, AT24CM01 and AT25M01 device families available in 8L SOIC (.150in) package at MTAI assembly site.

CCB No.: 8400.001

Misc.	Assembly site	MTAI
	BD Number	BD-004597/01
	MP Code (MPC)	669024C2XS00
	Part Number (CPN)	25CSM01-E/SN
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	100
	Reliability Site	MTAI
Lead-Frame	Paddle size	95 x 130
	Material	CDA194
	DAP Surface Prep	Cu-RT
	Treatment	Roughened
	Process	Stamped
	Lead-lock	Yes
	Part Number	10100842
	Lead Plating	Matte Tin
Bond Wire	Material	CuPdAu
Die Attach	Part Number	CRM-1064L (PFAS free)
	Conductive	Yes
MC	Part Number	G630AY
PKG	Package Type	SOIC
	Pin/Ball Count	8
	PKG width/size	150 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Standard Pb-free Solderability	J-STD-002E ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a min. 5 devices.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	JESD22-A103. +175°C for 504 hours or +150°C for 1008 hrs. Electrical test pre and post stress at +25°C and hot temp.	45	5	3	150	0	10	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. (MSL1/260)	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.